1

TRANSMITTAL FOR U.S. PATENT APPLICATION UNDER 37 CFR §1.53(b)

Mail Stop Patent Application COMMISSIONER OF PATENTS P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

| Transmitted | herewith f | for filing is | the original | patent app | lication of: |
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Inventor: Antonio L.P. Rotondaro, et al.

Filing Date: December 15, 2003

For: METHOD OF FABRICATING A DIELECTRIC LAYER

with PTO 1449 (1 page with one reference)

FOR A SEMICONDUCTOR STRUCTURE

| Enclos | sed are: |
|----------|---|
| X | _ Specification, Claims and Abstract (27 Pages); |
| X | _ Drawing(s) 1 _ Total Sheet(s) of X _ Formal Informal; |
| X | Combined Declaration and Power of Attorney (1 Page) X Newly executed (original or copy); |
| _X | An Assignment (1 Page) of the invention to Texas Instruments Incorporated is attached. A separate cover sheet (2 Pages) in compliance with 37 C.F.R. §§ 3.28, .31 is included. Please charge the assignment recordal fee of \$40.00 pursuant to 37 C.F.R. § 1.21(h) to Deposit Account No. 20-0668 of Texas Instruments Incorporated; |
| <u>X</u> | _ Certificate of Mailing (1 Page); |
| X | Texas Instrument Incorporated Return Receipt Postcard (1); |
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| X | _ This Transmittal (2 pages); and |
| x | Information Disclosure Statement (2 pages) |

2

| Applic | ant is: |
|----------|---|
| X | Large Entity |
| | Small Entity |
| The ac | companying application is: |
| <u>X</u> | Original. |
| | Continuation Divisional Continuation-In-Part (CIP) of prior application No which is hereby incorporated by reference therein. |

| | FEE | | | | |
|-----------------------|-----------|------|-----------------|-------------|------------------------|
| | Number | | Number Extra | Rate | Basic Fee \$ 770.00 |
| Total Claims | 20 | - 20 | 0 | X \$18.00 = | \$ 0.00 |
| Independent Claims | 4 | -3 | 1 . | X \$86.00 = | \$ 86.00 . |
| | \$ 856.00 | | | | |

X Please charge the filing fee of \$856.00 and any other fee required by this paper and credit any overpayment to Deposit Account No. 20-0668 of TEXAS INSTRUMENTS INCORPORATED. This document is being transmitted in duplicate.

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Antonio L.P. Rotondaro, et al.

Filing Date:

December 15, 2003

Title:

Method Of Fabricating A Dielectric Layer For A

Semiconductor Structure

Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Dear Sir:

CERTIFICATE OF MAILING BY EXPRESS MAIL

I hereby certify that the attached Filing Fee Transmittal (2 pages), Patent Application (27 pages), Formal Drawings (1 Sheet), Declaration and Power of Attorney (1 page), Assignment (1 page), Assignment transmittal form (2 pages), Information Disclosure Statement (2 pages), Form PTO-1449 (one page with one reference), Baker Botts L.L.P. return receipt postcard (1 card), Texas Instruments Incorporated return receipt postcard (1 card), and this Certificate of Mailing are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 C.F.R. § 1.10 on this 15th day of December, 2003 and is addressed to the Mail Stop Patent Application, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Willie Tiles

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